Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

AICROCHIP			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
Semiconductor Device Type: 006_UDFN_1.6x1.6x0.6_NiPdAu (HKA)  "Contained In"		% Total	<del></del>						-	
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	1.90	(mg) Total	Mold Compound	% ot Total Weight	43.27
Silica, fused	60676-86-0	Mold Compound	38.943	1.713	389,430		Silica, fused	60676-86-0	90.00	
Epoxy Resin	Trade Secret	Mold Compound	2.099	0.092	20,986		Epoxy Resin	Trade Secret	4.85	
Phenolic Resin	Trade Secret	Mold Compound	2.099	0.092	20,986		Phenolic Resin	Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound	0.130	0.006	1,298		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	39.027	1.717	390,270			Total	100.00	
Iron	7439-89-6	Lead Frame	0.923	0.041	9,225	1.76	(mg) Total	Lead Frame	% of Total Weight	40.11
Phosphorous	7723-14-0	Lead Frame	0.100	0.004	1,003		Copper	7440-50-8	97.30	
Zinc (Metal)	7440-66-6	Lead Frame	0.060	0.003	602		Iron	7439-89-6	2.30	
Silver	7440-22-4	Die Attach	3.559	0.157	35,594		Phosphorous	7723-14-0	0.25	
Epoxy resin	68475-94-5	Die Attach	0.962	0.042	9,620		Zinc (Metal)	7440-66-6	0.15	
Copper(II) oxide	1317-38-0	Die Attach	0.144	0.006	1,443			Total	100.00	
Gamma-butyrolactone	96-48-0	Die Attach	0.144	0.006	1,443	0.21	(mg) Total	Die Attach	% of Total Weight	4.81
Silicon	7440-21-3	Chip (Die)	9.670	0.425	96,700		Silver	7440-22-4	74.00	
Gold	7440-57-5	Wire Bond	1.120	0.049	11,200		Epoxy resin	68475-94-5	20.00	
Nickel	7440-02-0	Plating on external leads (pins)	0.918	0.040	9,180		Copper(II) oxide	1317-38-0	3.00	
Palladium	7440-05-3	Plating on external leads (pins)	0.051	0.002	510		Gamma-butyrolactone	96-48-0	3.00	
									100.00	
Gold	7440-57-5	Plating on external leads (pins)	0.051	0.002	510			Total	100.00	
Gold	7440-57-5	Plating on external leads (pins)  TOTALS:	0.051 <b>100.000</b>	0.002 <b>4.400</b>	510 <b>1.000.000</b>	0.43	Total (mg)			9.67
	0.0044 g	TOTALS: Total Mass EU Directives: 2002/95/EC (27 January 2003) &	100.000	4.400	1,000,000	0.43	Total (mg)  Doped Silicon	Total  Chip (Die)  7440-21-3  Total	% of Total Weight 100.00 100.00	9.67
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